

Notice of References Cited	Application/Control No. 10/717,219	Applicant(s)/Patent Under Reexamination FARIS, SADEG M.	
	Examiner Tuan Quach	Art Unit 2814	Page 1 of 1

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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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